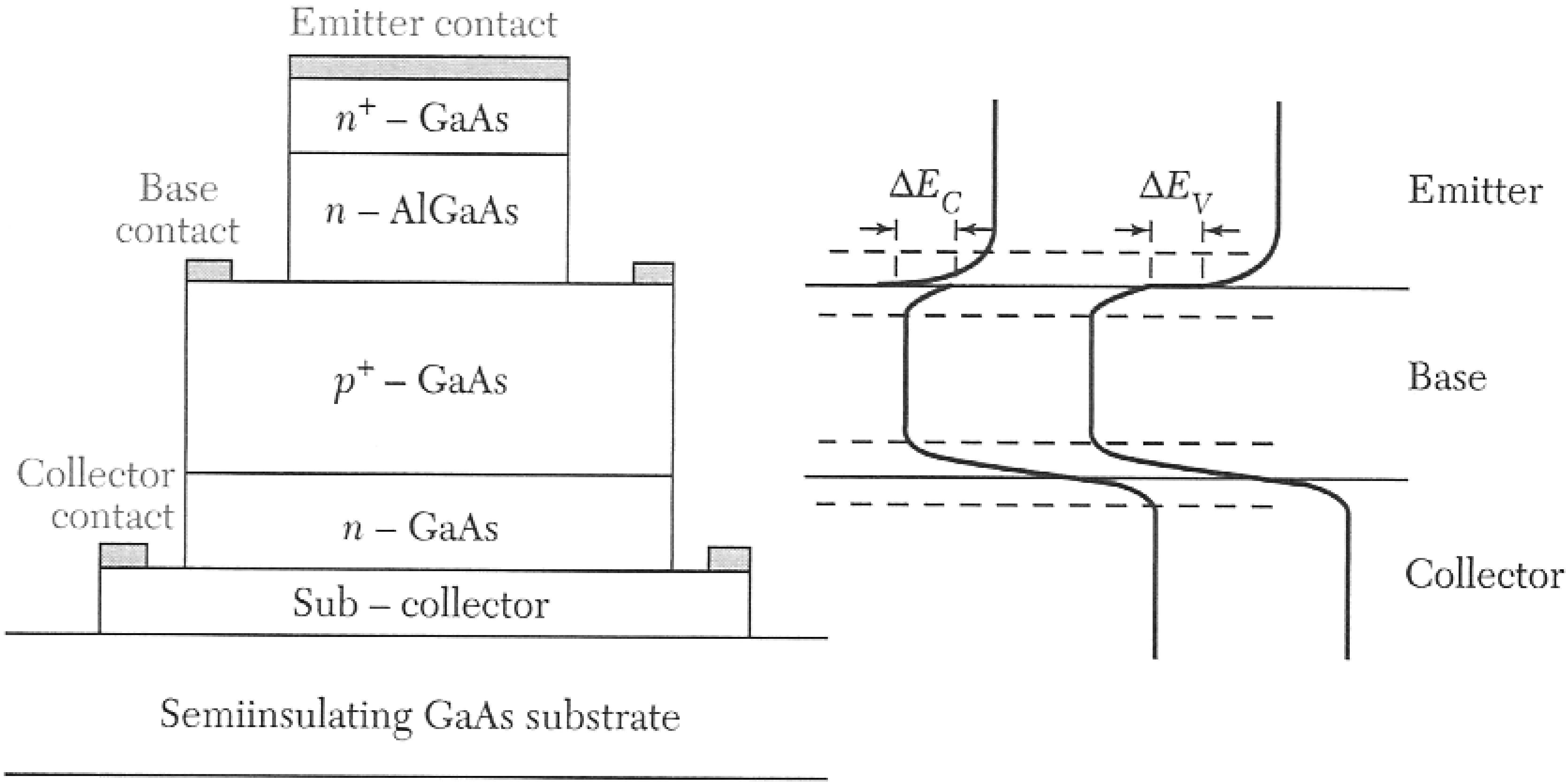
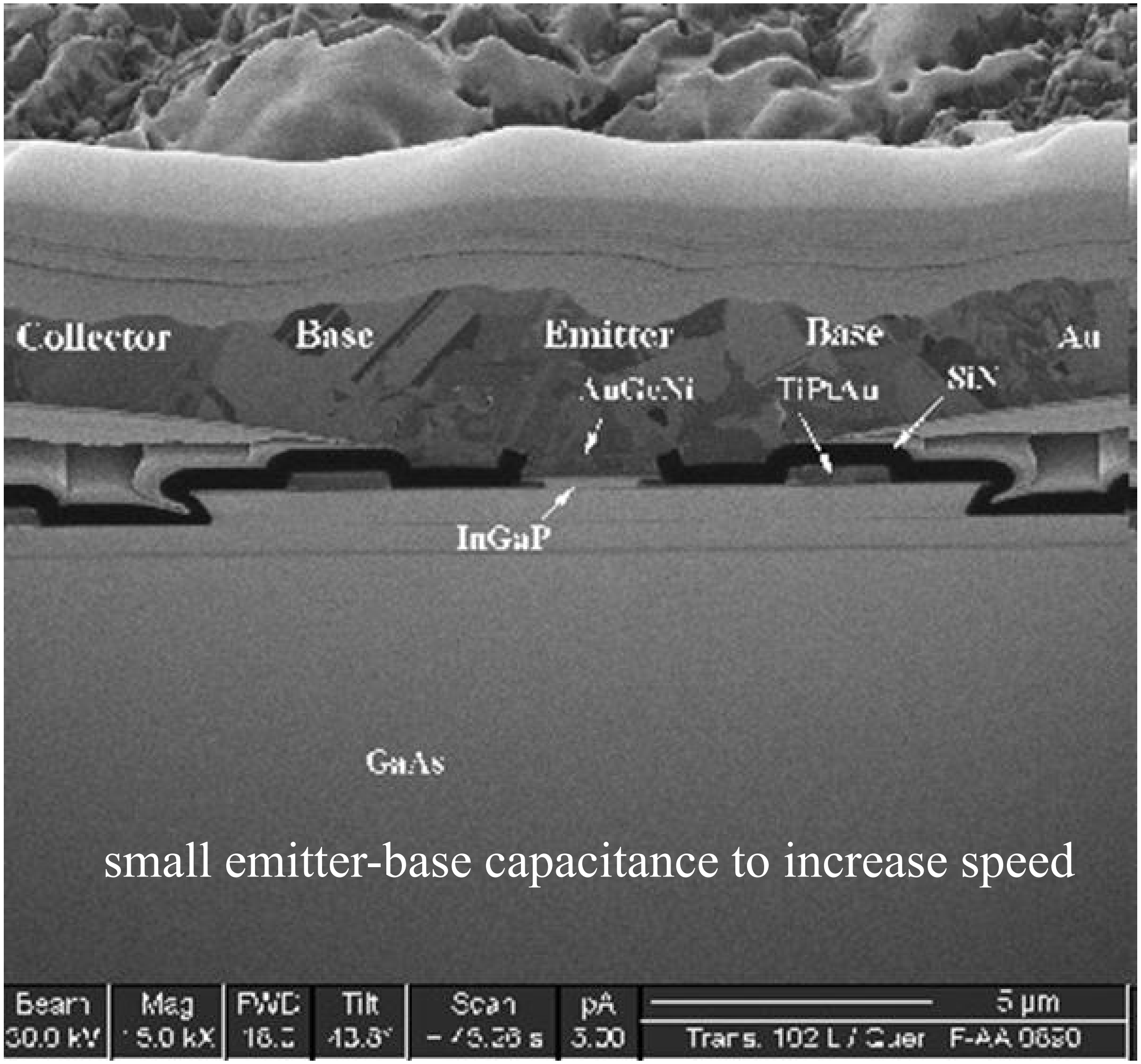
13. Bipolar transistors
Optoelectronics

Jan. 22, 2020

Heterojunction bipolar transistors



Heterojunction bipolar transistor



small emitter-base capacitance to increase speed

HBT current gain

$$I_C = \beta I_B$$

$$\beta = \frac{\alpha}{1-\alpha} \approx \frac{n_{B0}}{p_{E0}} \qquad \text{(npn)}$$

Higher doping in the emitter makes the minority carrier concentration lower in the emitter.

$$n_{B0} = \frac{n_i^2}{N_A} = \frac{N_C N_V \exp(-E_{gB}/k_B T)}{N_A}$$

$$p_{E0} = \frac{n_i^2}{N_D} = \frac{N_C' N_V' \exp(-E_{gE}/k_B T)}{N_D}$$

If the emitter and the base have different band gaps

$$\beta = \frac{N_E}{N_B} \frac{N_c N_v}{N_c' N_v'} \exp\left(\frac{\Delta E_g}{k_B T}\right) \sim 100000$$

HBT current gain

A HBT has an emitter bandgap of 1.62 and a base bandgap of 1.42.
A BJT has an emitter bandgap of 1.42 and a base bandgap of 1.42.
Both have an emitter doping of 10^{18} cm^{-3} and a base doping of 10^{15}cm^{-3}.
How much larger is the gain in the HBT?

$$\frac{\beta(\mathrm{HBT})}{\beta(\mathrm{BJT})}=\exp\left(\frac{\Delta E_g}{k_B T}\right)=\exp\left(\frac{1.62-1.42}{0.0259}\right)=2257$$

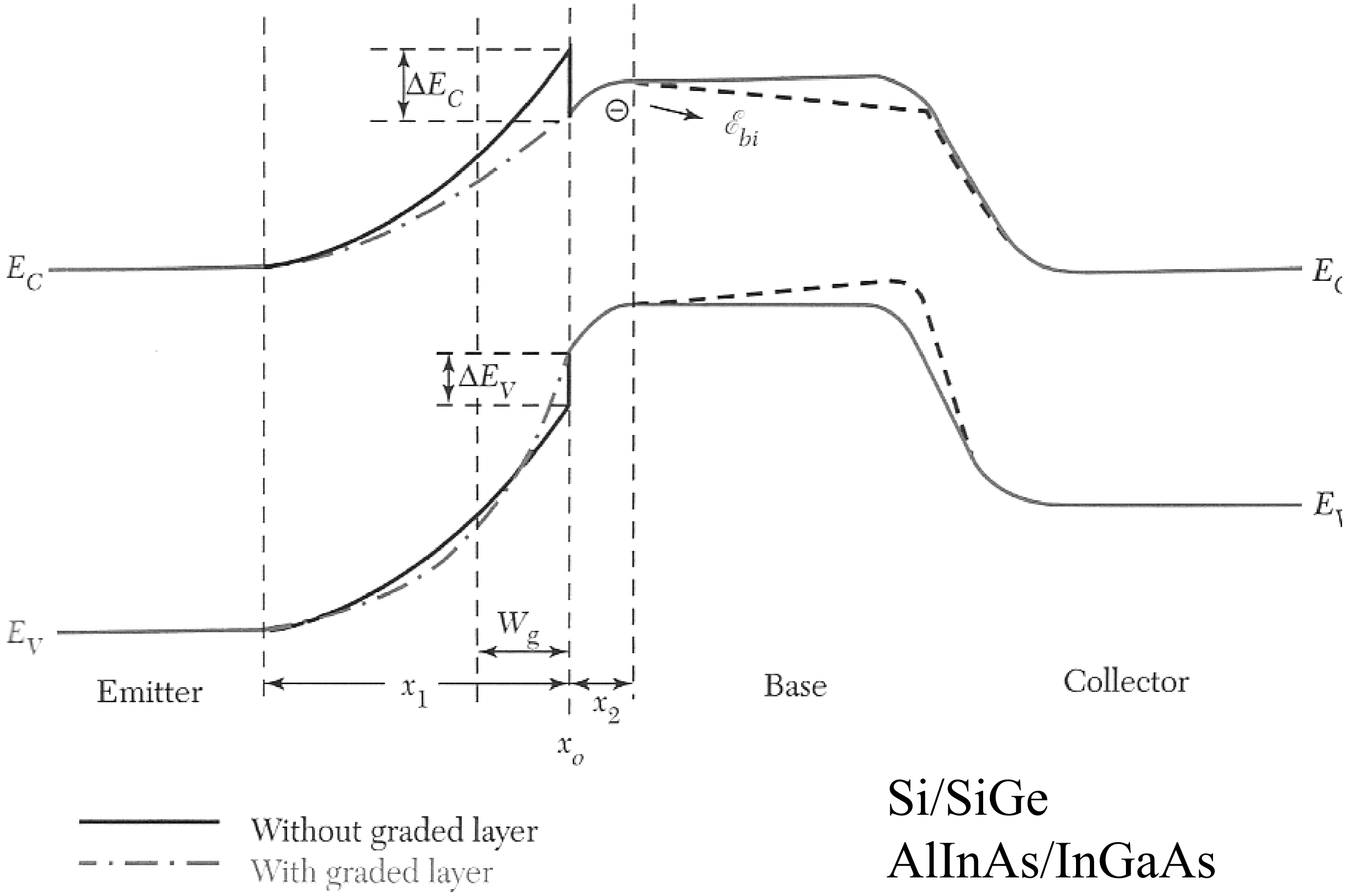
HBT

Trade off gain for higher speed

Higher base doping
- lower base resistance
- reduced Early effect
- less trouble with punch through
- base can be made thinner -> faster transistors

Because of higher base doping, a higher collector doping is possible without punch through
- lower collector resistance

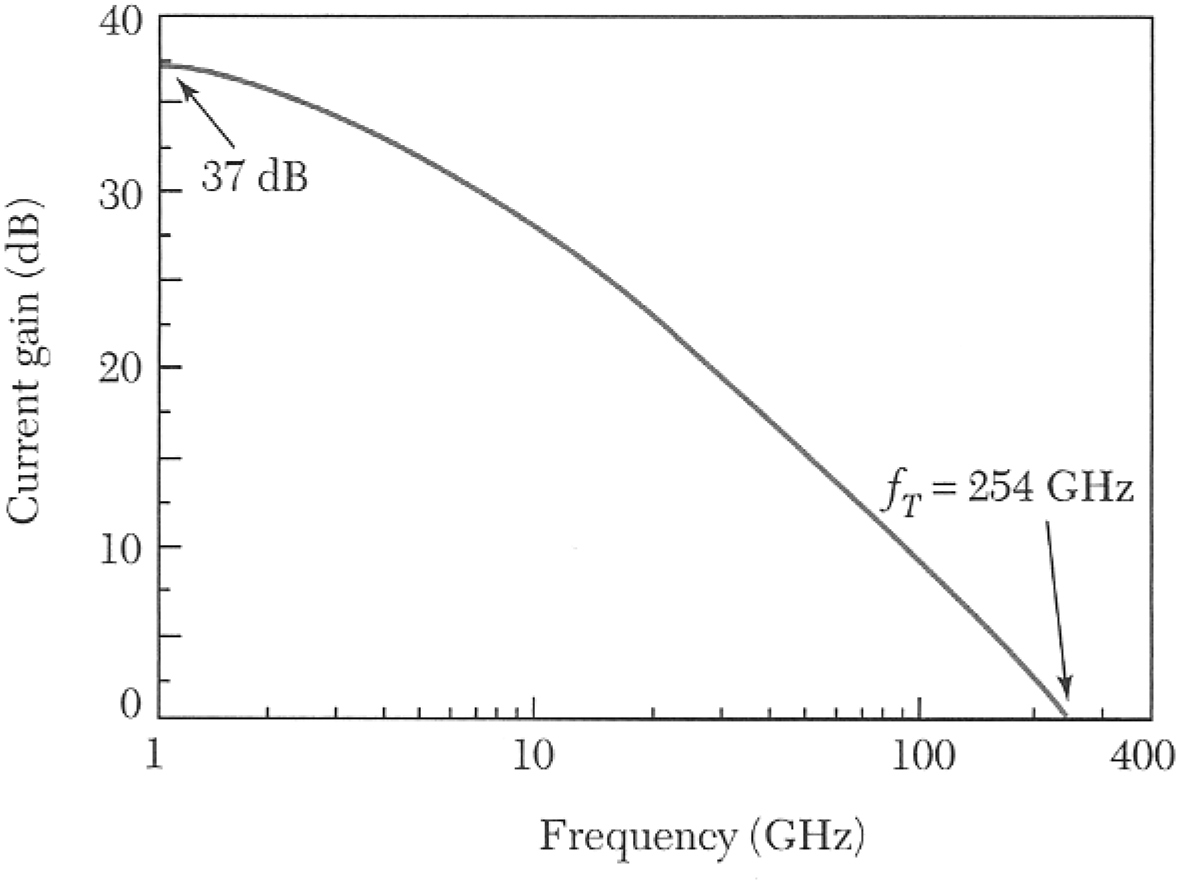
HBT current gain



Si/SiGe
AlInAs/InGaAs

band discontinuity reduces emitter efficiency
Graded layer emitter and base improve performance

Heterojunction bipolar transistors



Fastest InP/InGaAs HBT's have an f_T of 710 GHz.

Higher doping in the base allows for a thinner base without punch through and lower base resistance and thus higher frequency operation

Microwave engineering

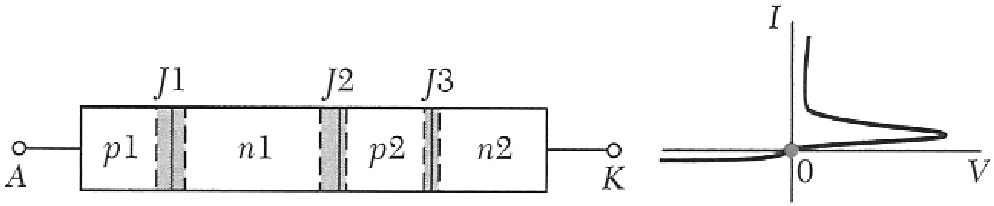
Electronics: $L \ll \lambda$ $f \lesssim 10$ GHz

Microwave: $\lambda < L$ 10 GHz $< f <$ 1 THz

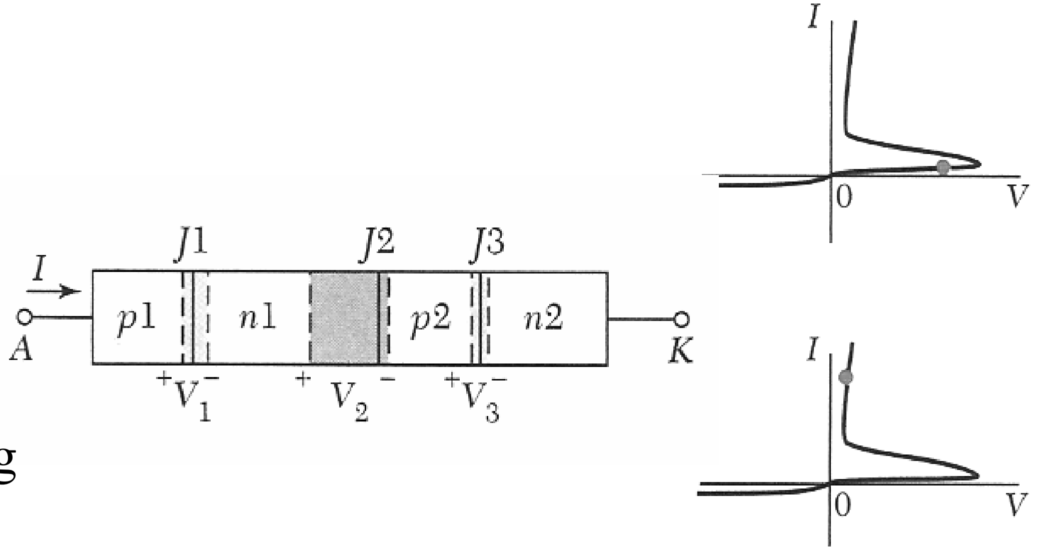
TeraHertz: $\lambda \ll L$ 1 THz $< f <$ 100 THz

Optics: $\lambda \ll L$ 100 THz

Thyristors

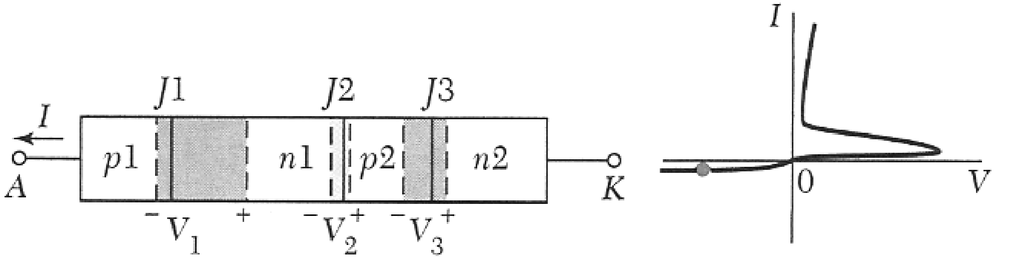


Forward blocking

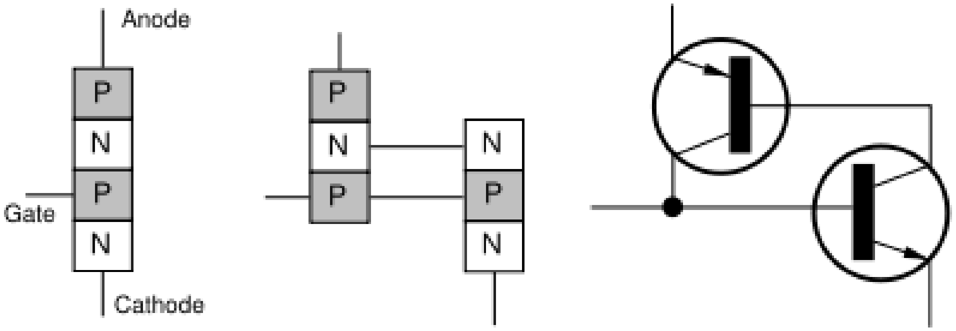


Forward conducting

Reverse blocking



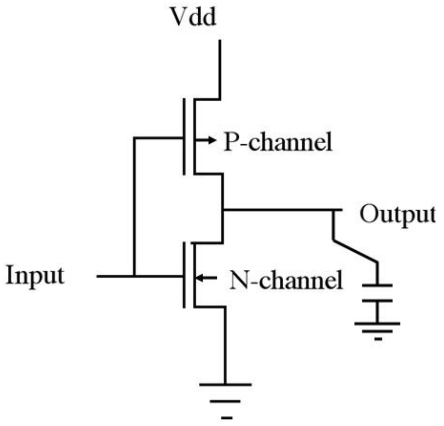
Thyristors

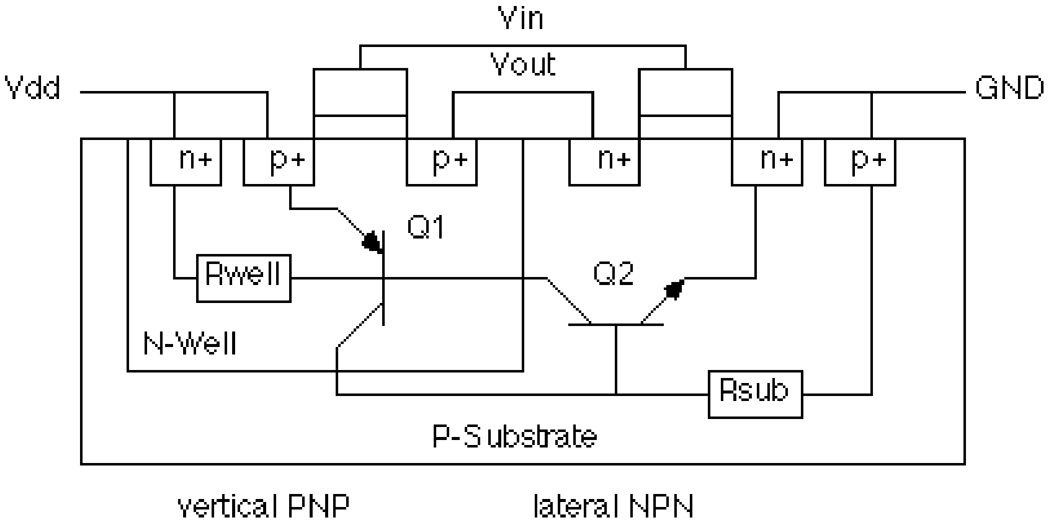


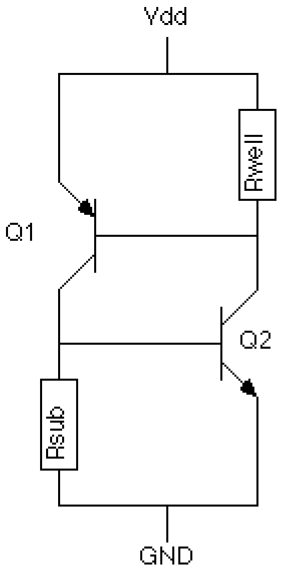
$\beta_1 * \beta_2 > 1$

Used for switching high currents or voltages

Latch-up



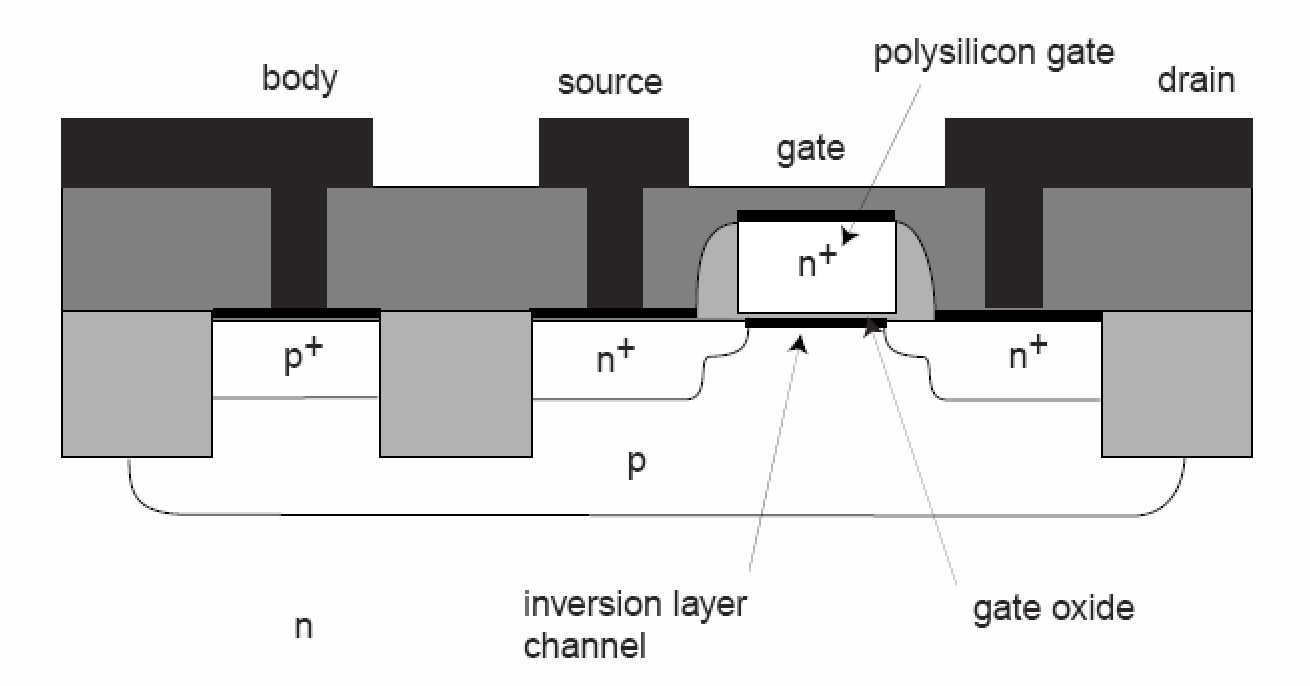




Both BJT's conduct, creating a low resistance path between V_{dd} and GND. The product of the gains of the two transistors in the feedback loop, is greater than one. The result of latchup is at the minimum a circuit malfunction, and in the worst case, the destruction of the device.

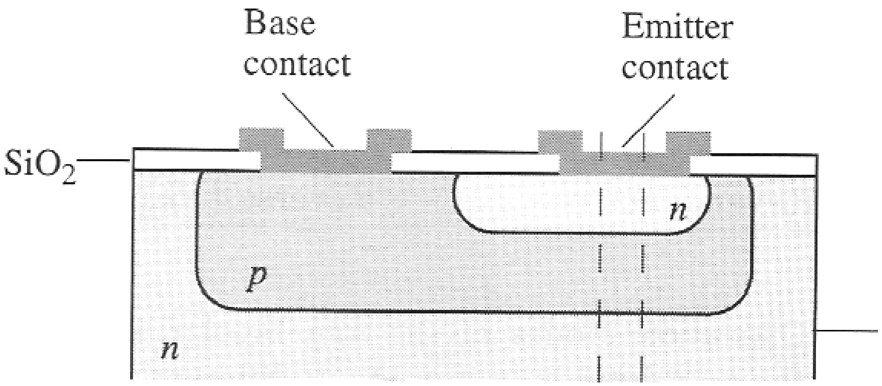
http://www.ece.drexel.edu/courses/ECE-E431/latch-up/latch-up.html

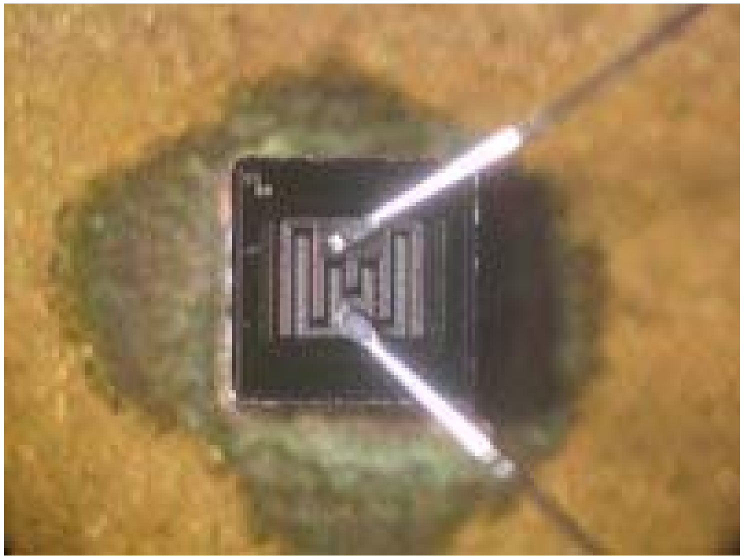
Subthreshold current



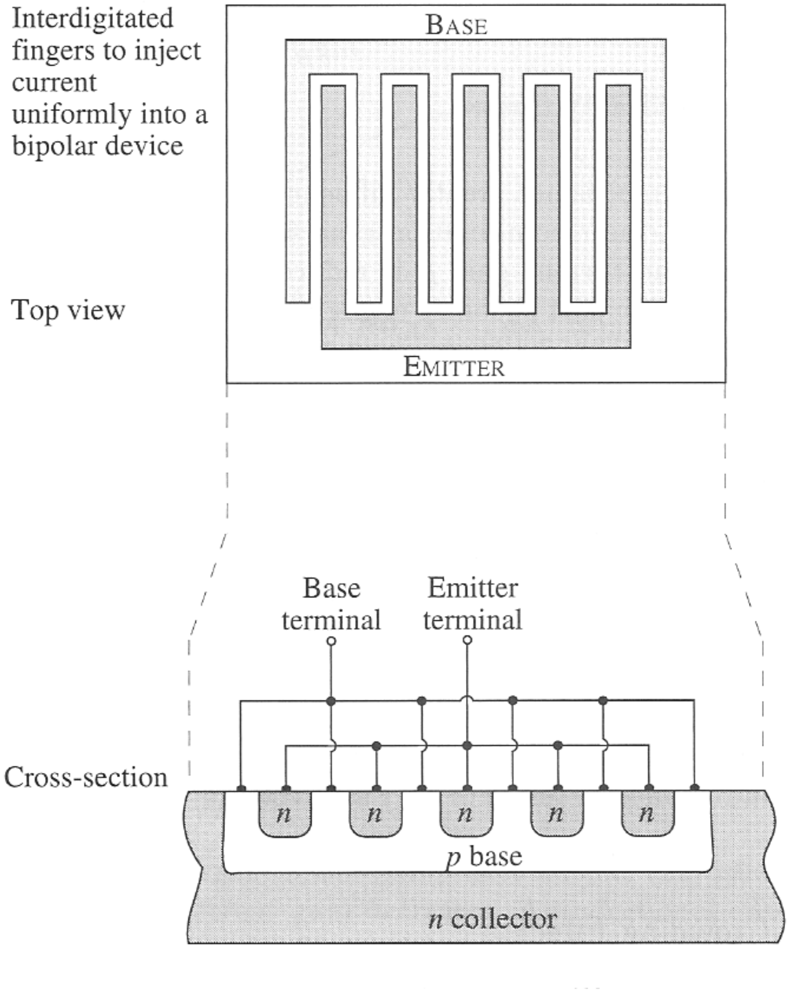
If the p-concentration in the channel is low, electrons emitted into the channel by the forward biased junction diffuse across the channel without recombining.

Interdigitated contacts in power transistors



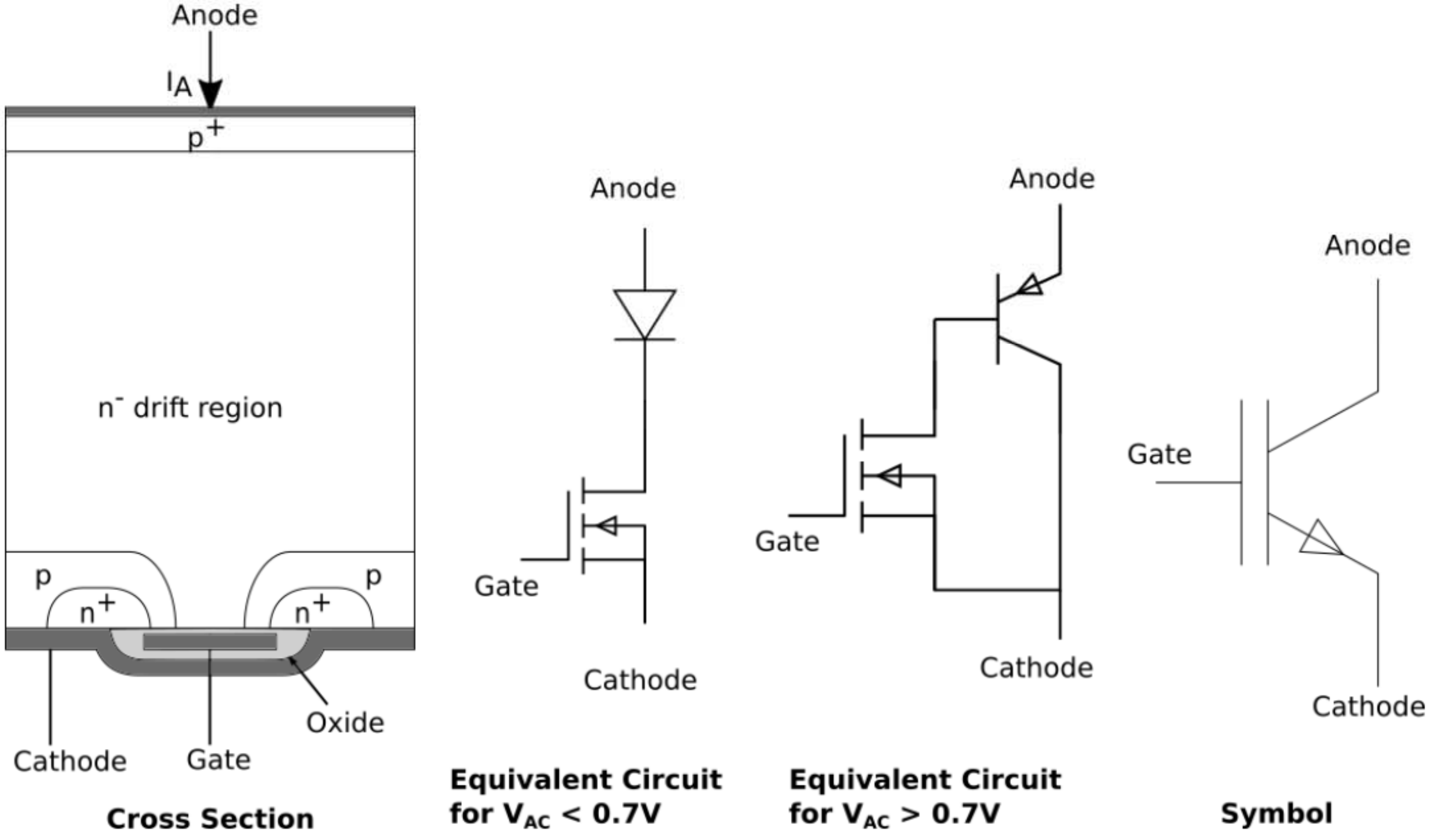


Interdigitated fingers to inject current uniformly into a bipolar device



IGBT - Insulated Gate Bipolar Transistor

An IGBT is a combination of an insulated gate FET and a bipolar transistor. It is primarily used for switching high power loads



Cross Section

Equivalent Circuit for V_{AC} < 0.7V

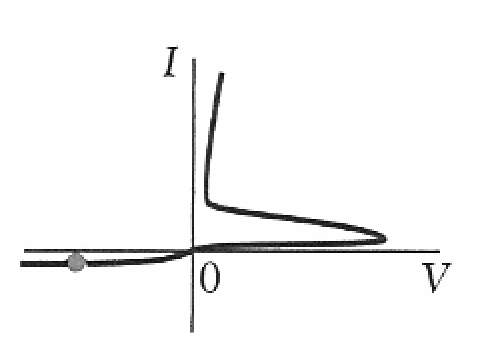
Equivalent Circuit for V_{AC} > 0.7V

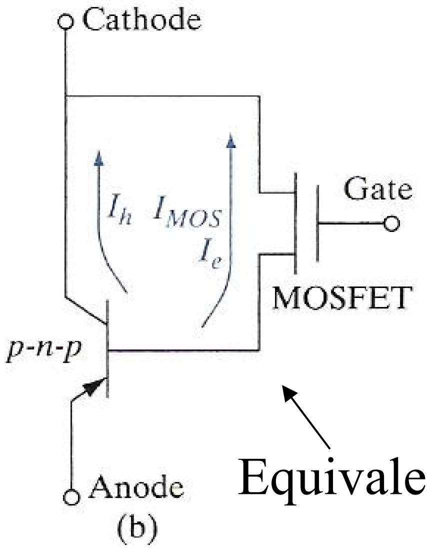
Symbol

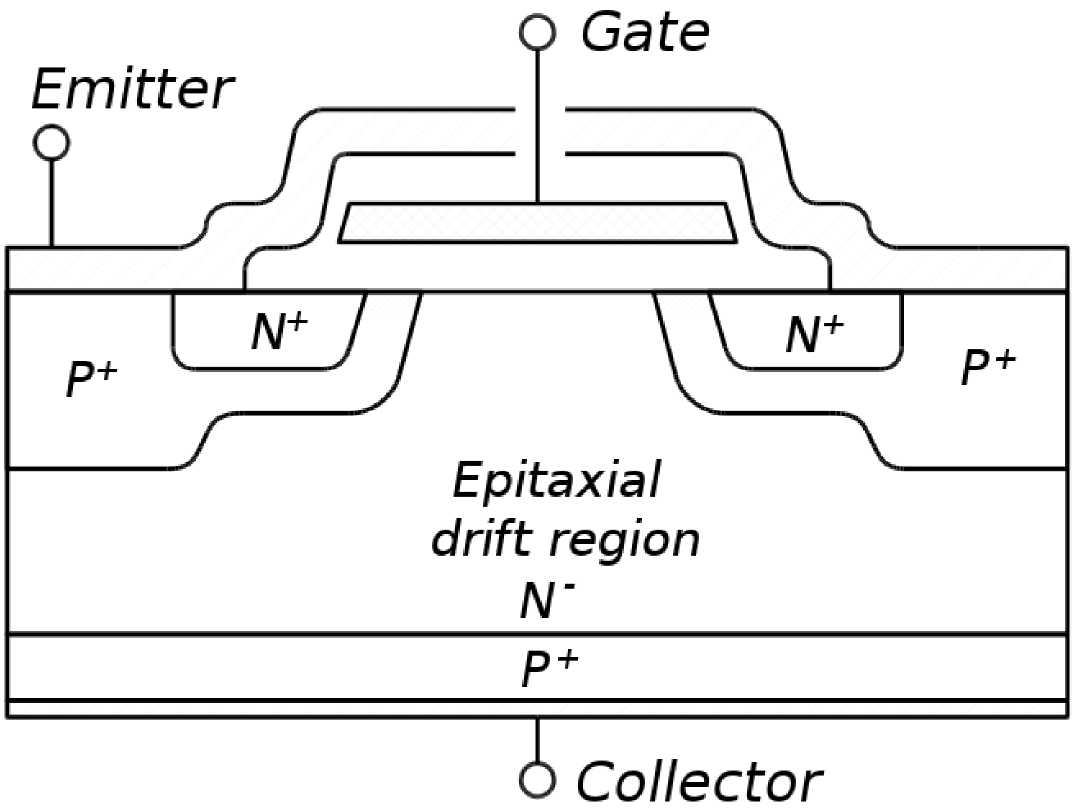
Used to switch large currents (in electric cars or trains).

http://lampx.tugraz.at/~hadley/psd/L13/igbt.html

Insulated gate bipolar transistor (IGBT)







Used to switch large currents (in electric cars or trains).

Equivalent circuit in the on-state. From Streetman.

BiCMOS

Only one additional step to CMOS is needed for BiCMOS

Bipolar junction transistors:
high speed
high gain
low output impedance
good for analog amplifiers

CMOS
high impedance
low power logic

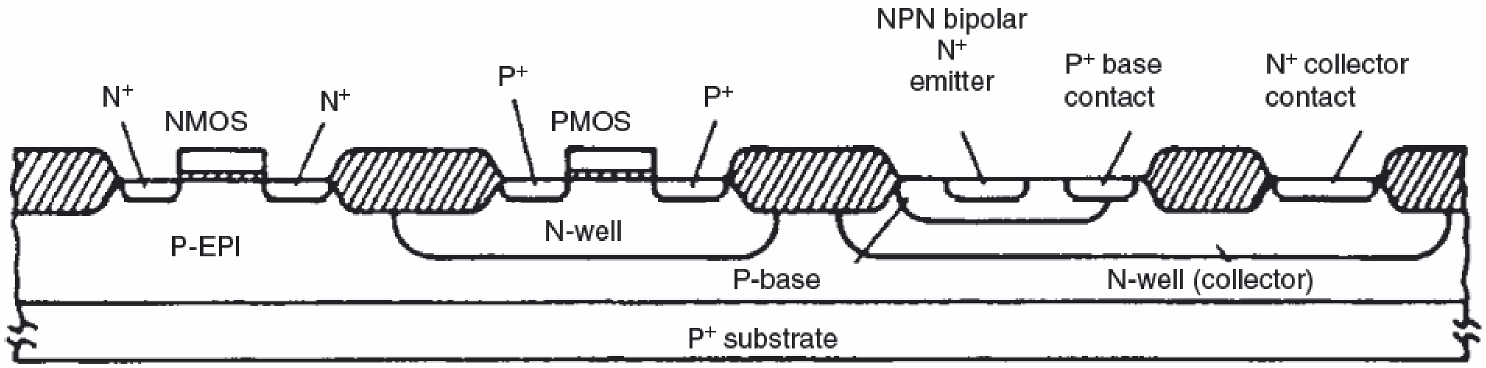


Figure 27.6 Simple BiCMOS technology: triple diffused-type bipolar transistor added to a CMOS process with minimal extra steps: only p-base diffusion mask is added to CMOS process flow. Reproduced from Alvarez (1989) by permission of Kluwer

Fransila

See: http://www.iue.tuwien.ac.at/phd/puchner/node48_app.html

Optoelectronics

Optoelectronics

light emitting diode
laser diode
solar cell
photo detectors

communications, memory (DVD), displays, printing, bar-code readers, solar energy, lighting, laser surgery, measurement, guidance, spectroscopy, LiFi

Photo detectors

Intrinsic semiconductor $\sigma = e(\mu_n n + \mu_p p)$ (used in copiers)

Unbiased pn junction - like a solar cell

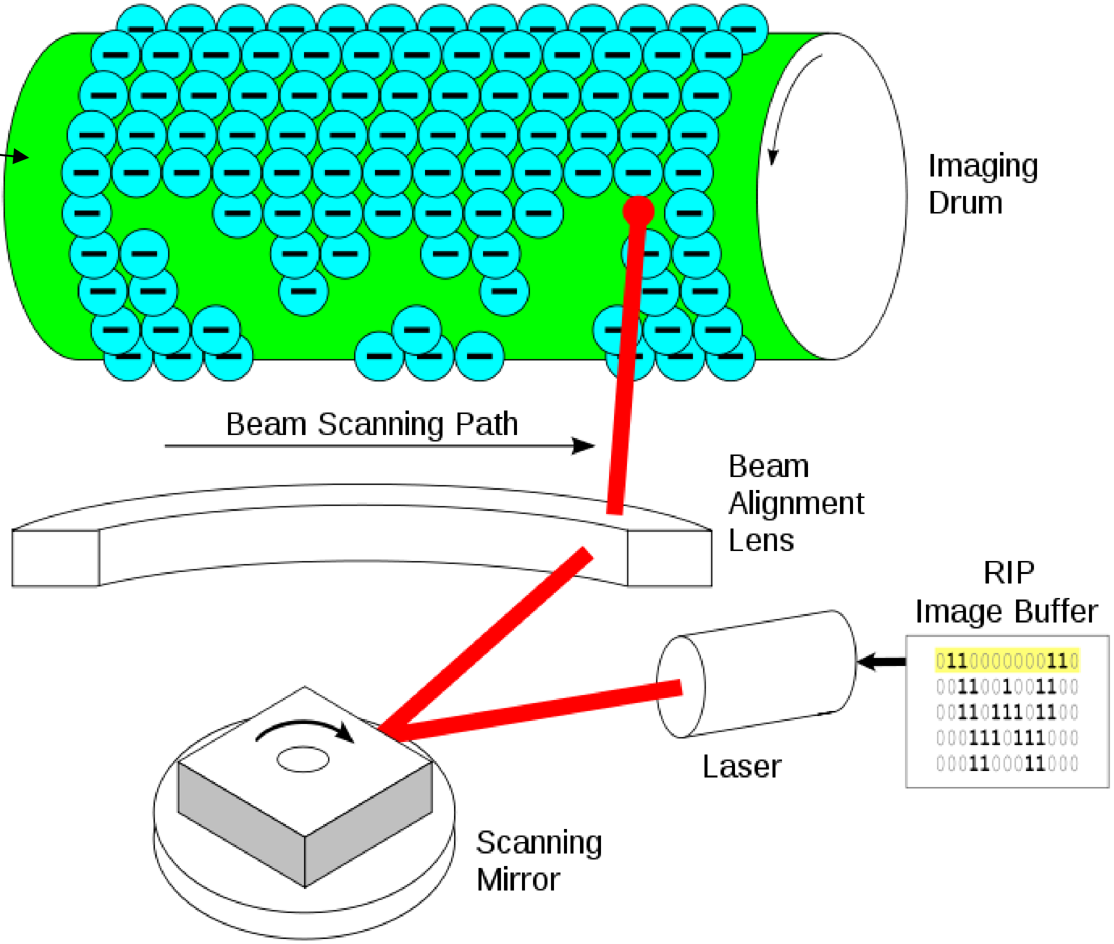
Reverse biased pn junction - smaller capacitance, higher speed, less noise

Phototransistor - light injects carriers into the base. This forward biases the emitter base junction. High responsivity.

Ambient light detectors.

Active Pixel sensors for automated parking and gesture control (uses time-of-flight to image in 3-D).

Laser printer

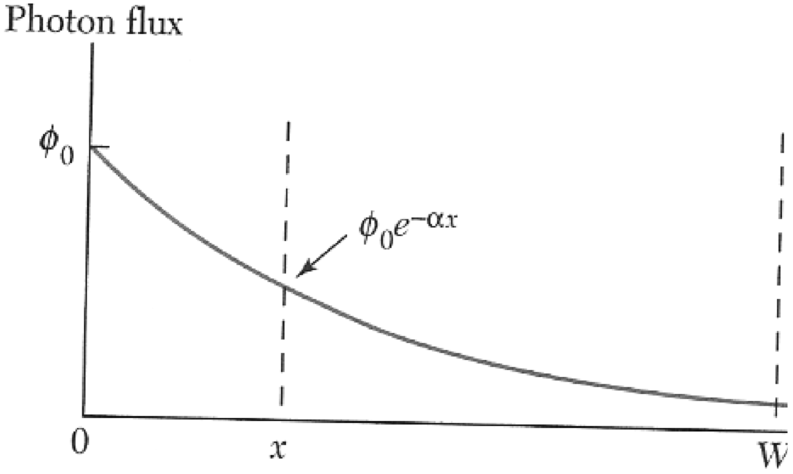


semiconducting
photoconductor

https://en.wikipedia.org/wiki/Laser_printing

Absorption

Photon flux: $\Phi(x) = \Phi_0 e^{-\alpha x}$

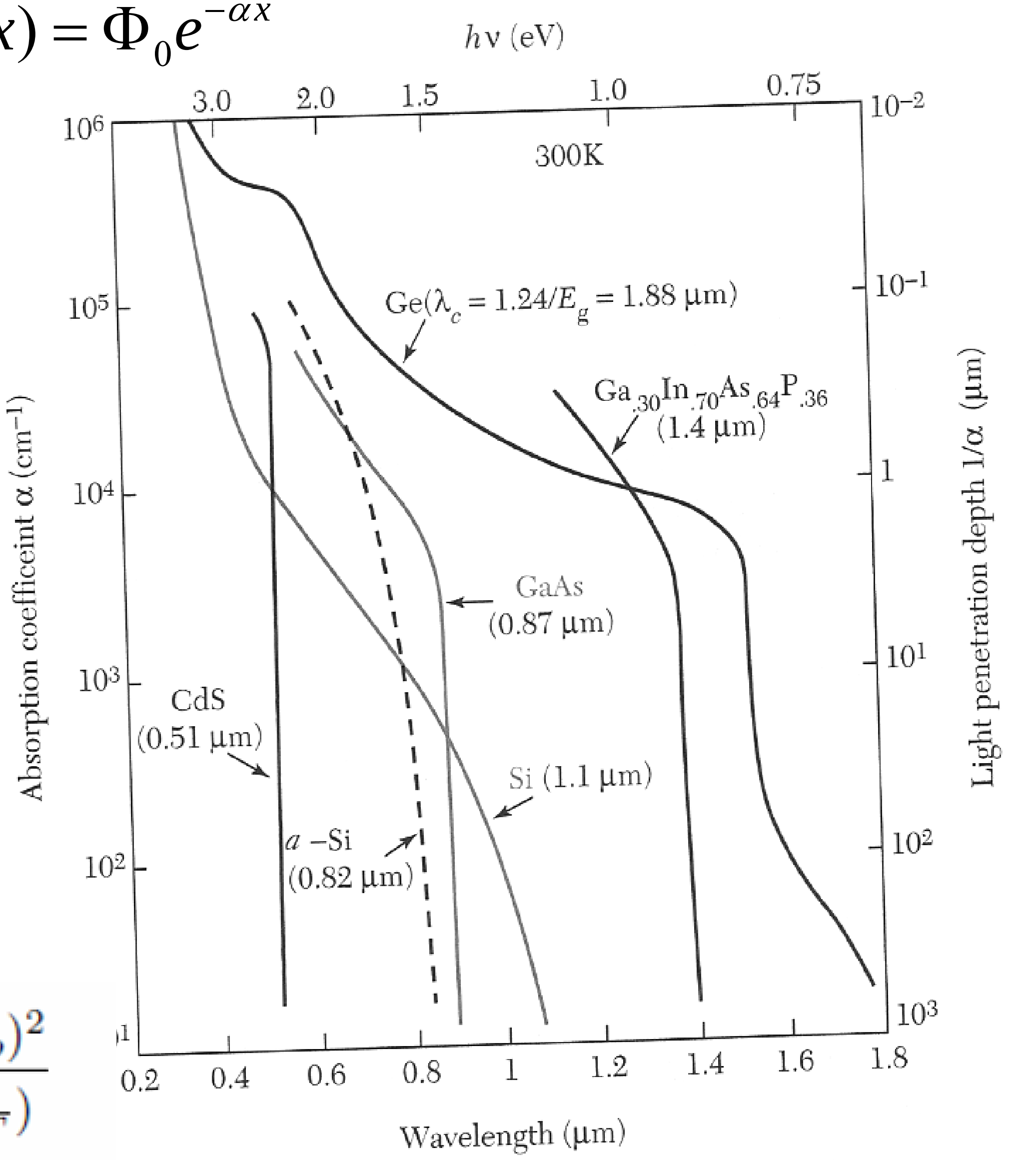


Sharp absorption edge for direct bandgap materials

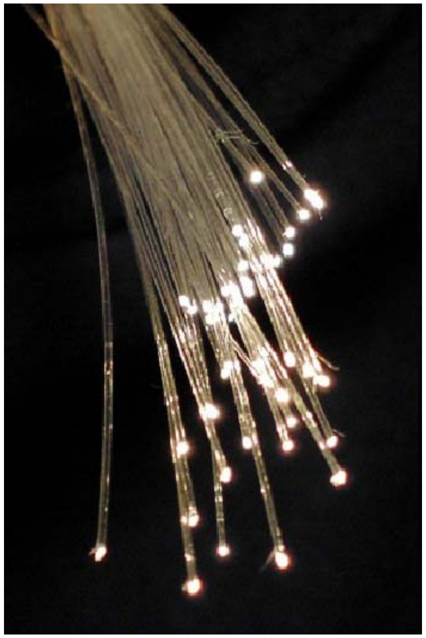
$$\alpha \approx 3.5\times10^{6}\left(\frac{m_r^*}{m_0}\right)^{3/2}\frac{\sqrt{\hbar\omega - E_g}}{\hbar\omega} \quad \text{cm}^{-1}$$

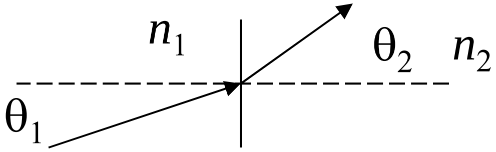
direct bandgap   indirect bandgap

$$\alpha \propto \frac{(h\nu - E_g + E_p)^2}{exp(\frac{E_p}{k_B T}) - 1} + \frac{(h\nu - E_g - E_p)^2}{1 - exp(-\frac{E_p}{k_B T})}$$

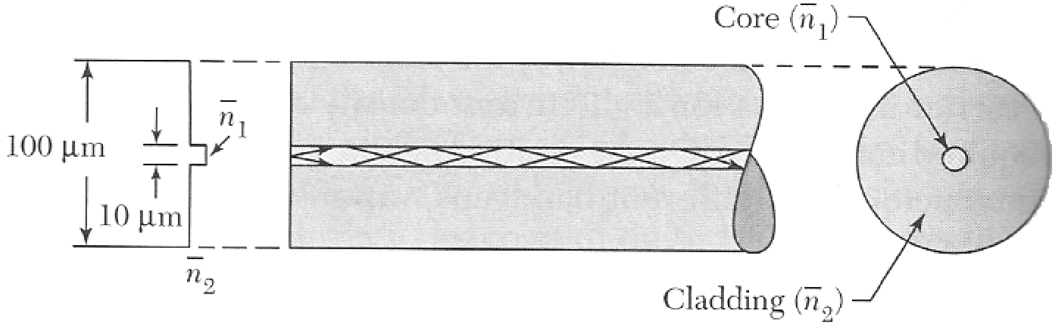


Confinement of light by total internal reflection

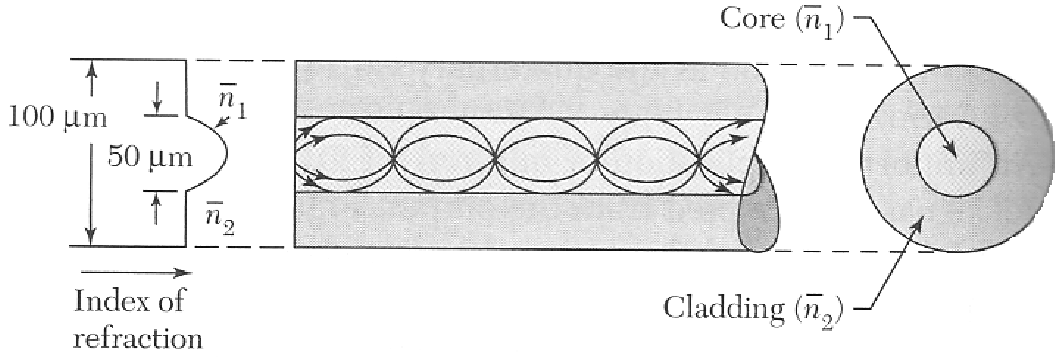




$$n_1\sin\theta_1 = n_2\sin\theta_2$$

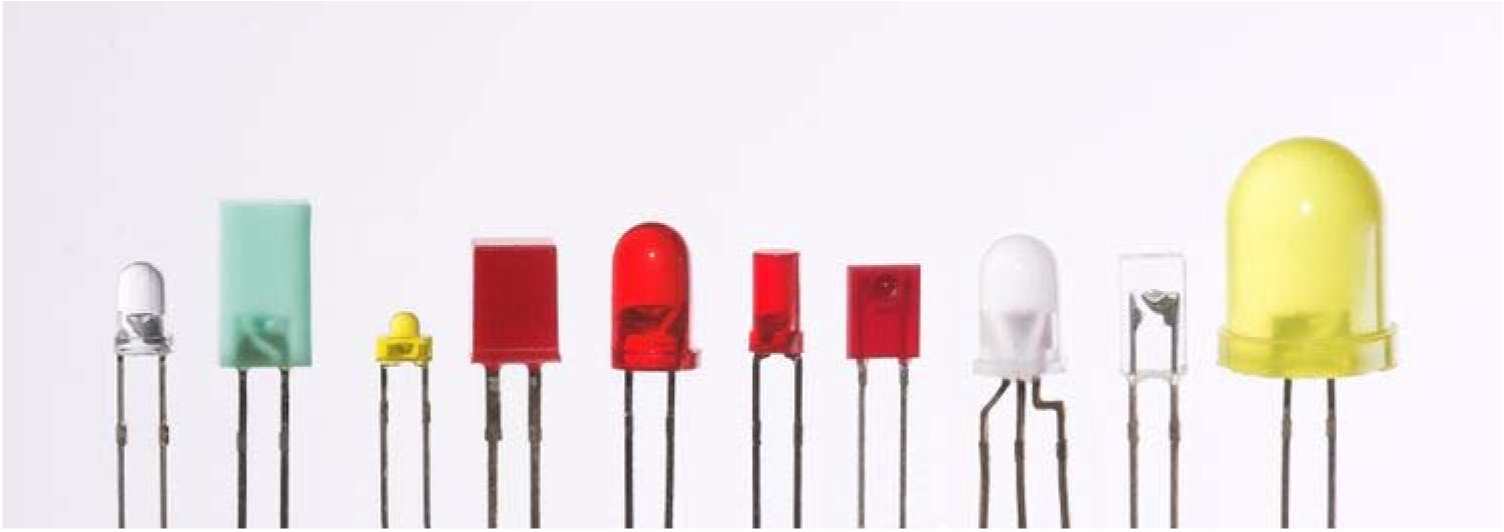


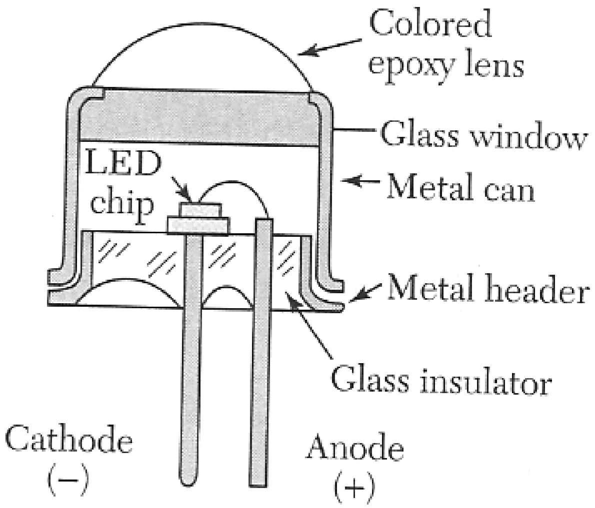
less pulse spreading for parabolically graded fiber

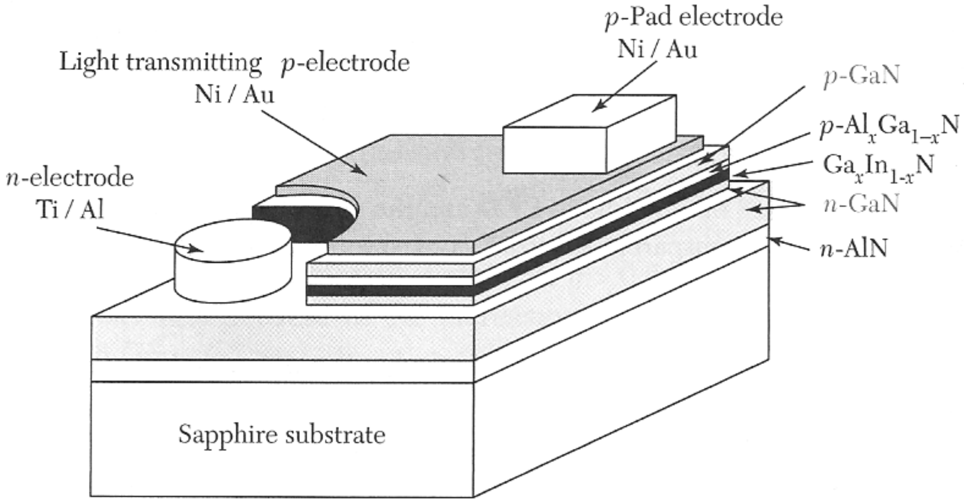


0.6 dB/km at 1.3 µm and 0.2 dB/km at 1.55 µm

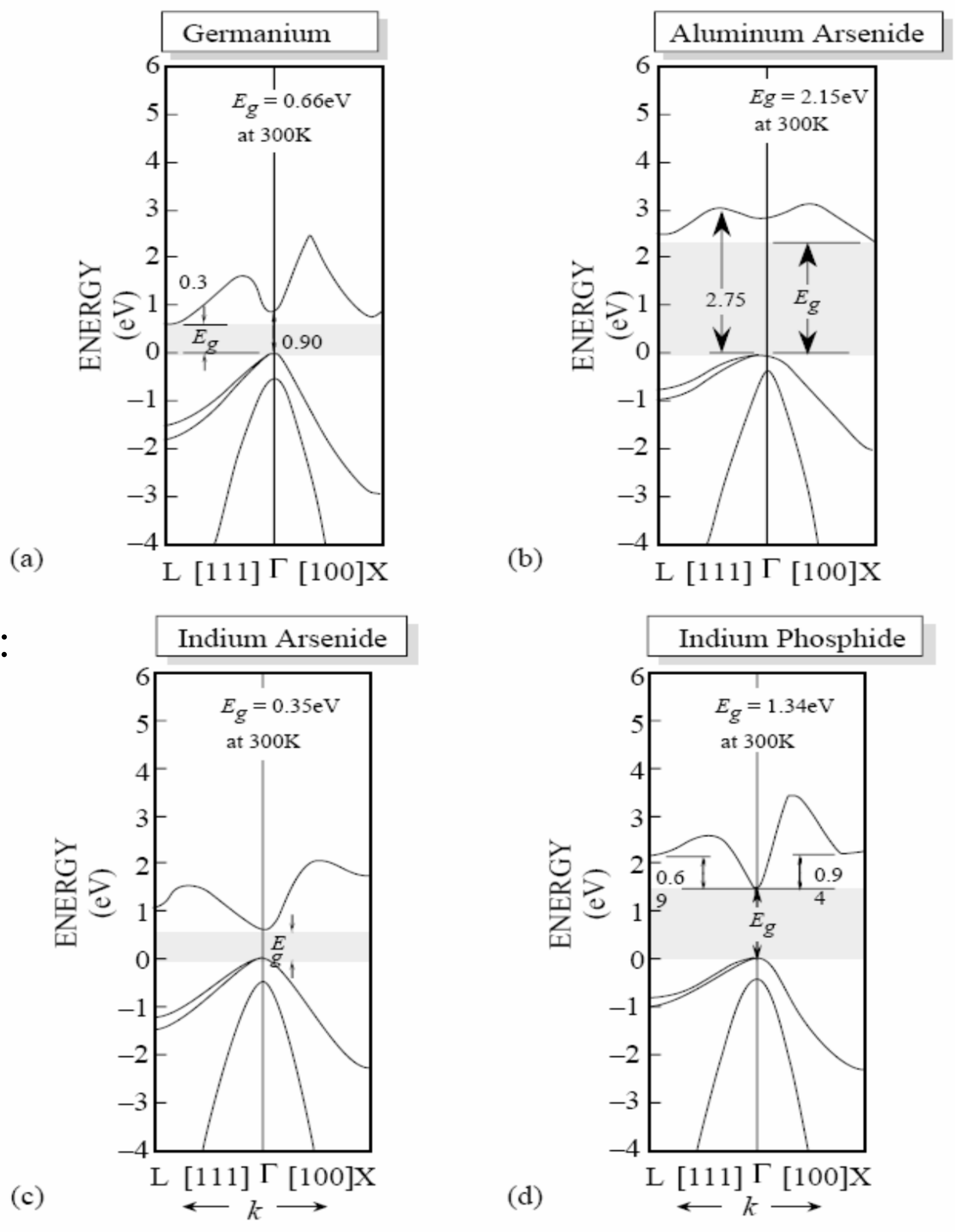
Light emitting diodes







Solid state lighting is efficient.



direct bandgap:
$\Delta k = 0$

photons can be emitted

indirect bandgap:
$\Delta k \neq 0$

phonons are emitted

Light emitting diodes

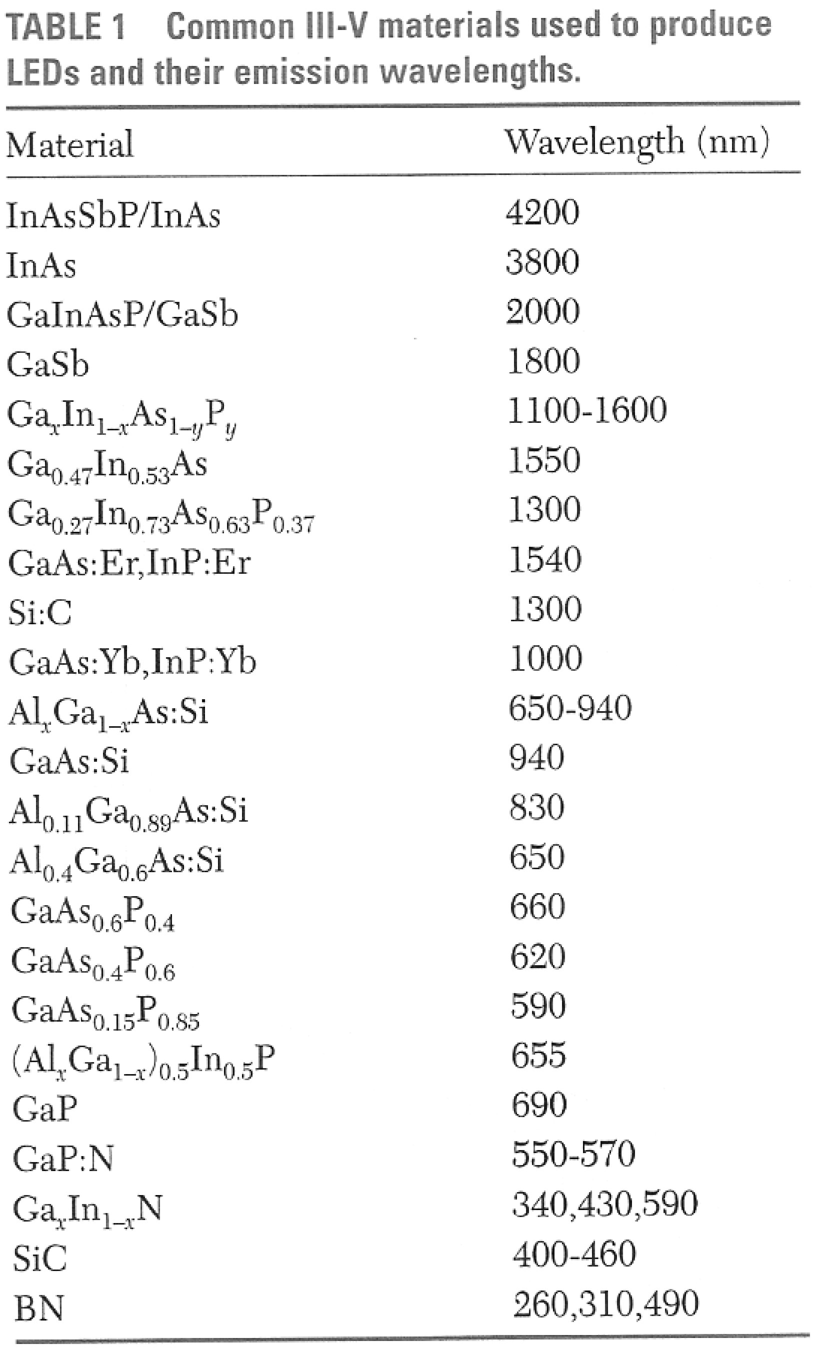
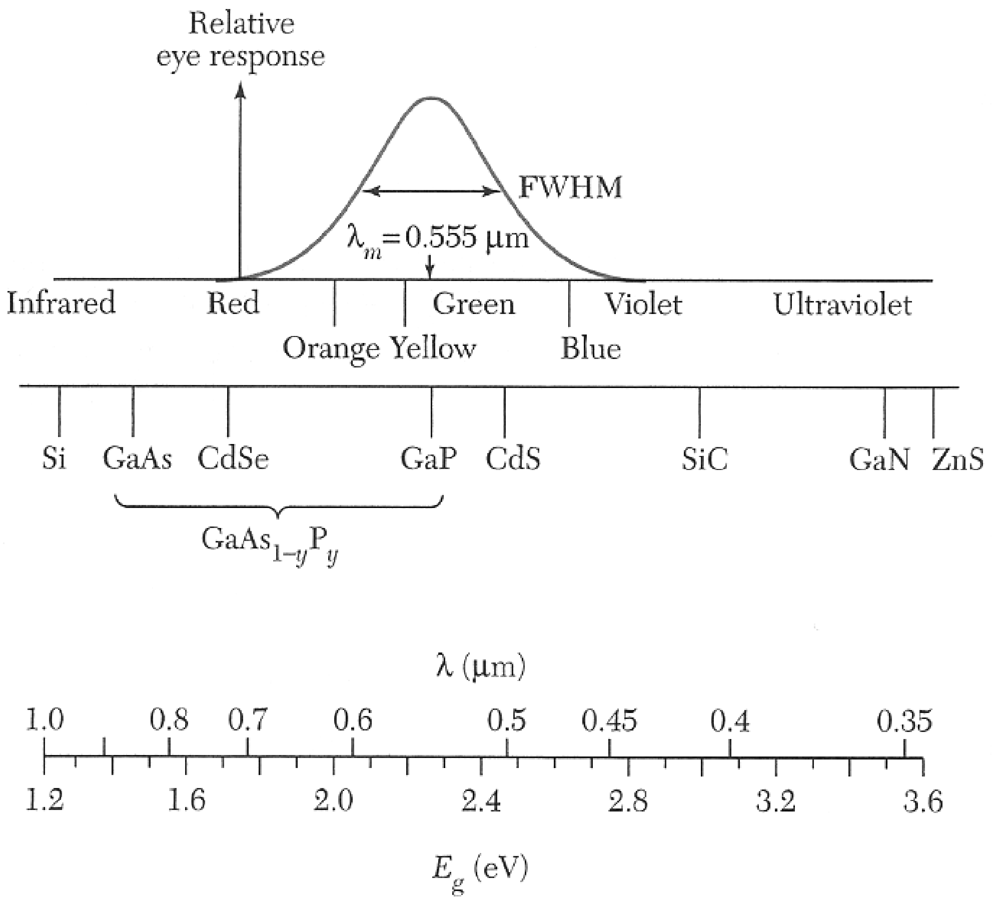
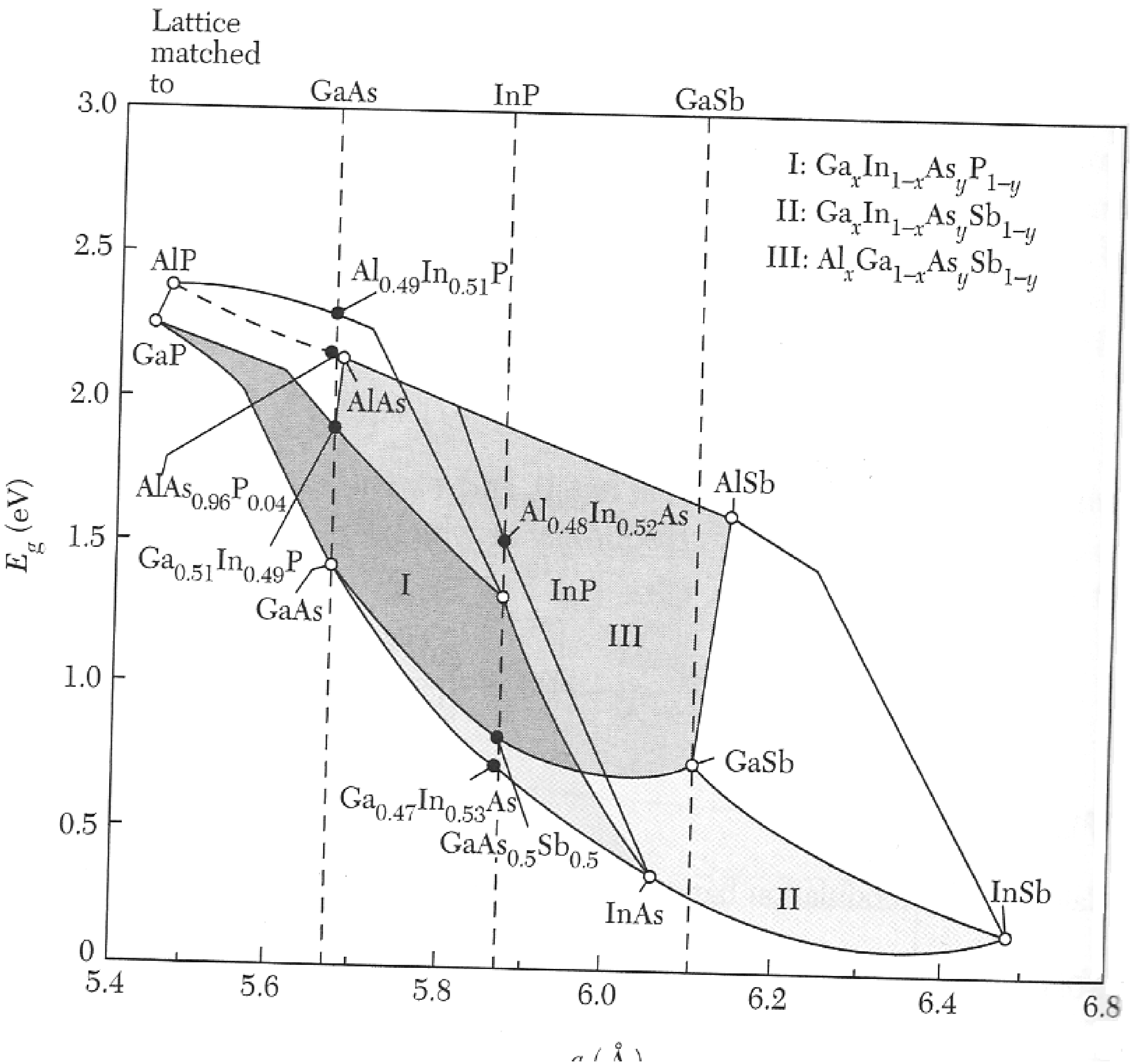


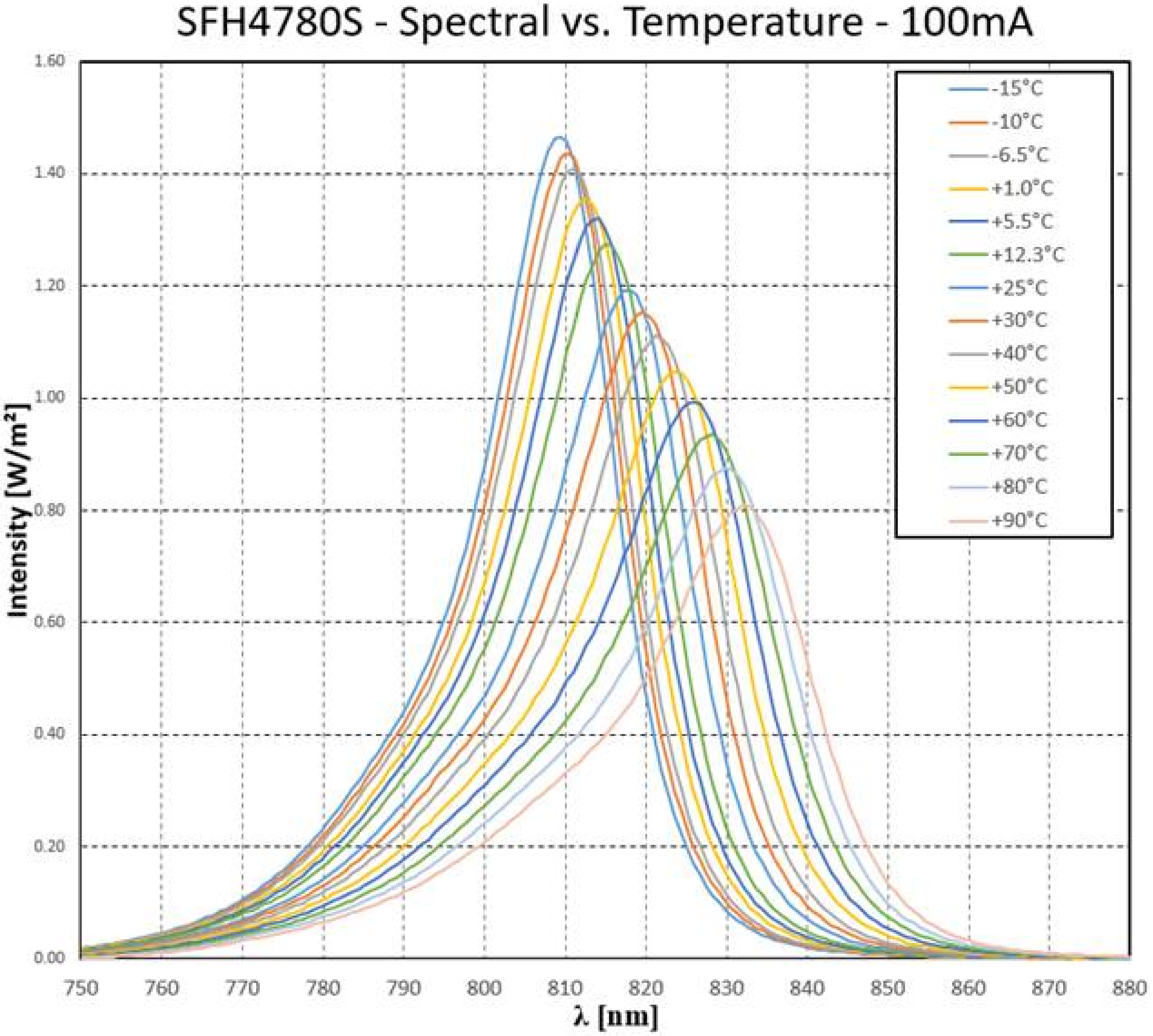
TABLE 1 Common III-V materials used to produce LEDs and their emission wavelengths.

Material	Wavelength (nm)
InAsSbP/InAs	4200
InAs	3800
GaInAsP/GaSb	2000
GaSb	1800
$Ga_xIn_{1-x}As_{1-y}P_y$	1100-1600
$Ga_{0.47}In_{0.53}As$	1550
$Ga_{0.27}In_{0.73}As_{0.63}P_{0.37}$	1300
GaAs:Er,InP:Er	1540
Si:C	1300
GaAs:Yb,InP:Yb	1000
$Al_xGa_{1-x}As$:Si	650-940
GaAs:Si	940
$Al_{0.11}Ga_{0.89}As$:Si	830
$Al_{0.4}Ga_{0.6}As$:Si	650
$GaAs_{0.6}P_{0.4}$	660
$GaAs_{0.4}P_{0.6}$	620
$GaAs_{0.15}P_{0.85}$	590
$(Al_xGa_{1-x})_{0.5}In_{0.5}P$	655
GaP	690
GaP:N	550-570
$Ga_xIn_{1-x}N$	340,430,590
SiC	400-460
BN	260,310,490



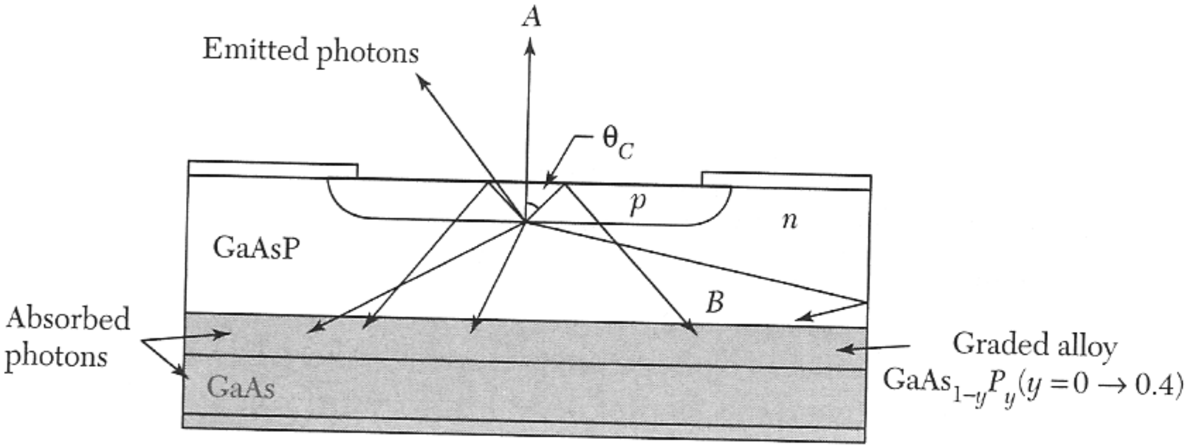

Lattice matched to
GaAs
InP
GaSb
I: $Ga_xIn_{1-x}As_yP_{1-y}$
II: $Ga_xIn_{1-x}As_ySb_{1-y}$
III: $Al_xGa_{1-x}As_ySb_{1-y}$
AlP
GaP
$Al_{0.49}In_{0.51}P$
AlAs
$AlAs_{0.96}P_{0.04}$
$Ga_{0.51}In_{0.49}P$
GaAs
I
$Al_{0.48}In_{0.52}As$
InP
III
AlSb
GaSb
$Ga_{0.47}In_{0.53}As$
$GaAs_{0.5}Sb_{0.5}$
InAs
II
InSb
E_g (eV)
3.0
2.5
2.0
1.5
1.0
0.5
0
5.4
5.6
5.8
6.0
6.2
6.4
6.8

IR LED

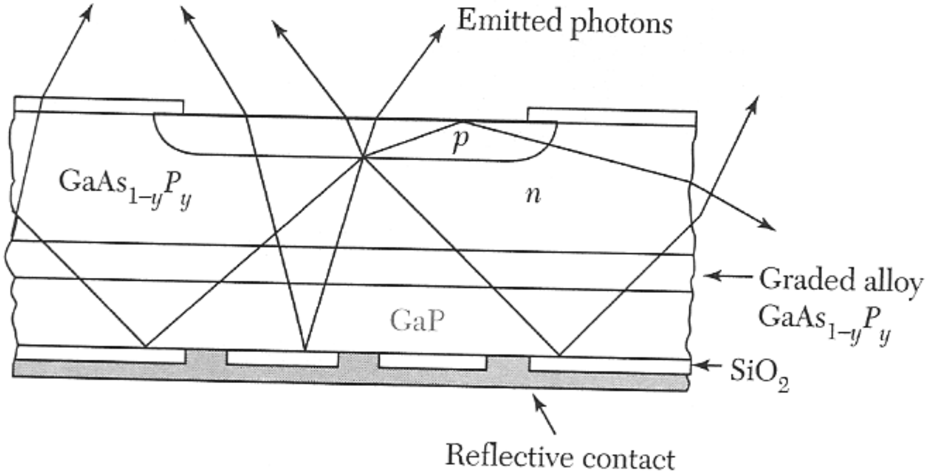


Measurement by Jan Enenkel

Light emitting diodes

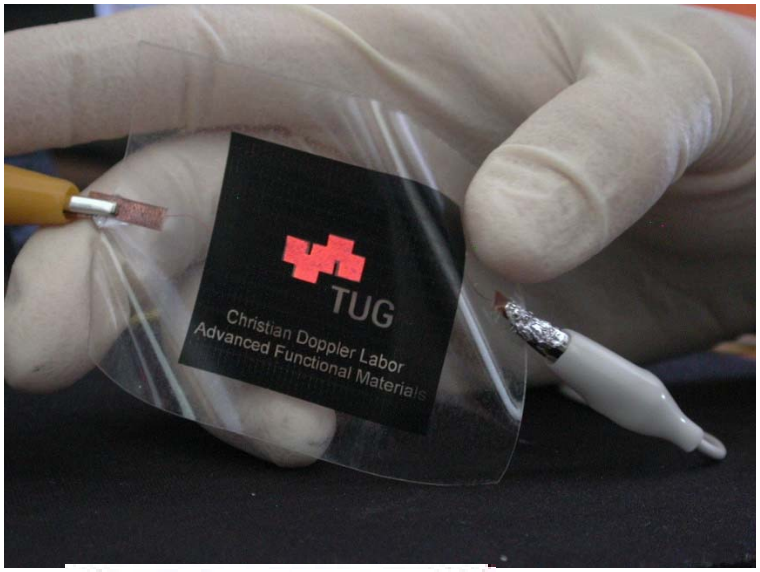


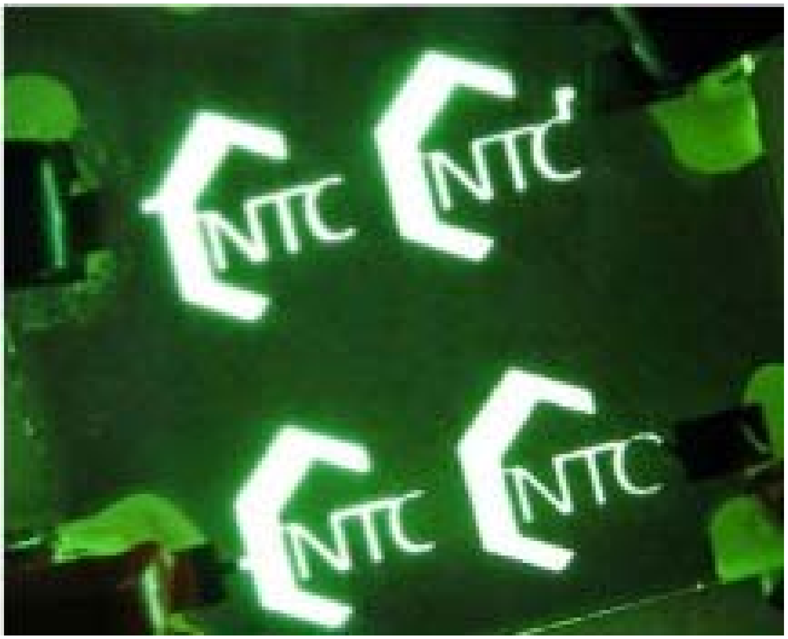
absorption
reflection
total internal reflection

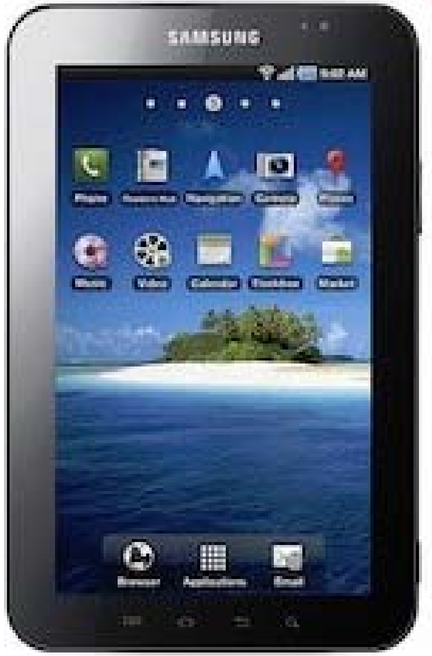


OLEDs

© 2012 CBS Interactive







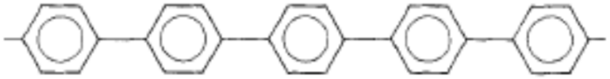
Galaxy Tab

Encapsulation technology

Electroluminescence in poly(p-phenylene)

Prof. Günther Leising

In 1992, Leising et al. for the first time reported on blue electroluminescence from OLEDs containing poly(p-phenylene) (PPP).

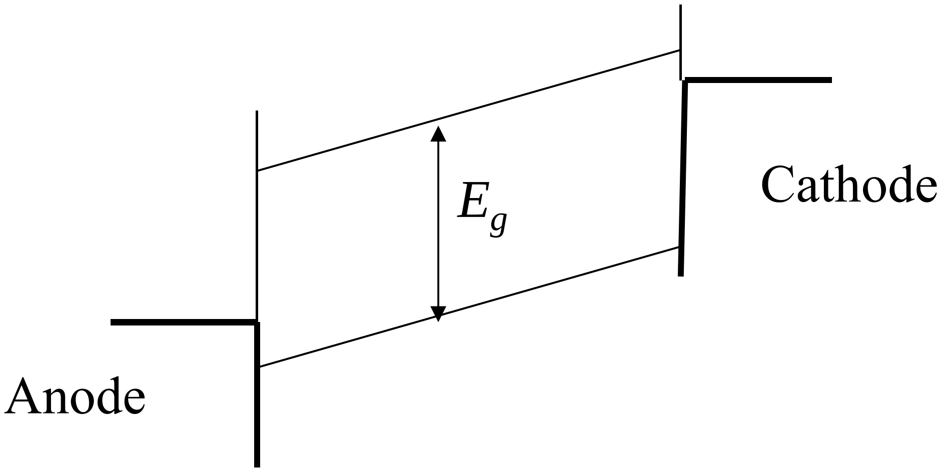


OLEDs

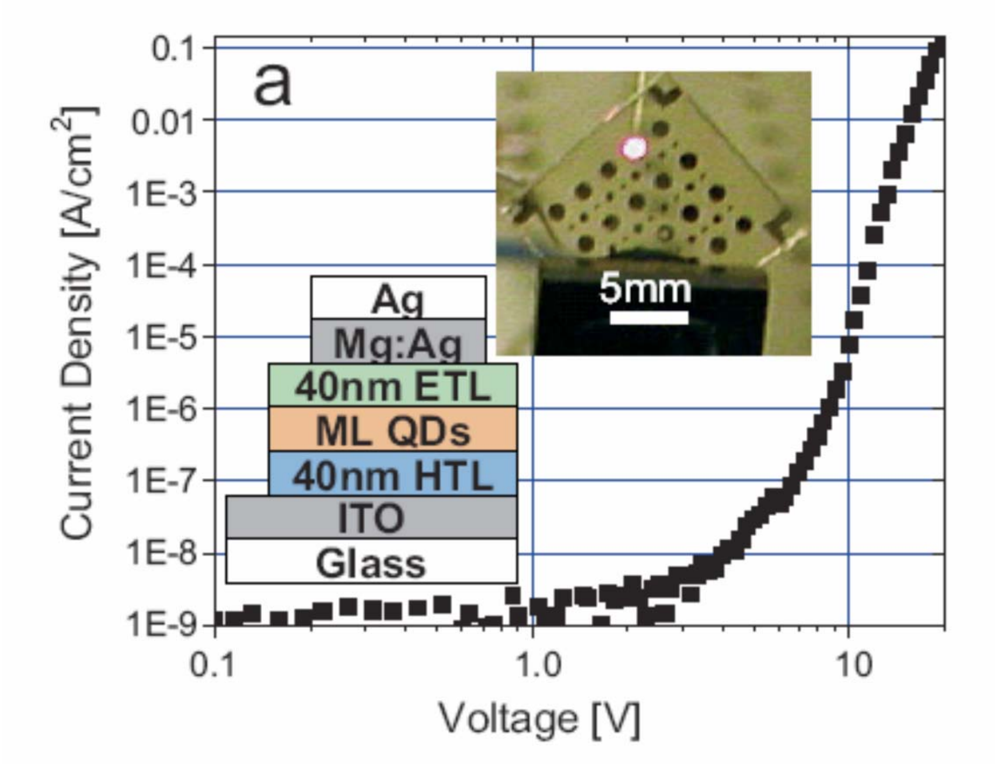
Aluminum cathode
Electron transport layer
Emission layer
Hole transport layer
ITO anode
Glass

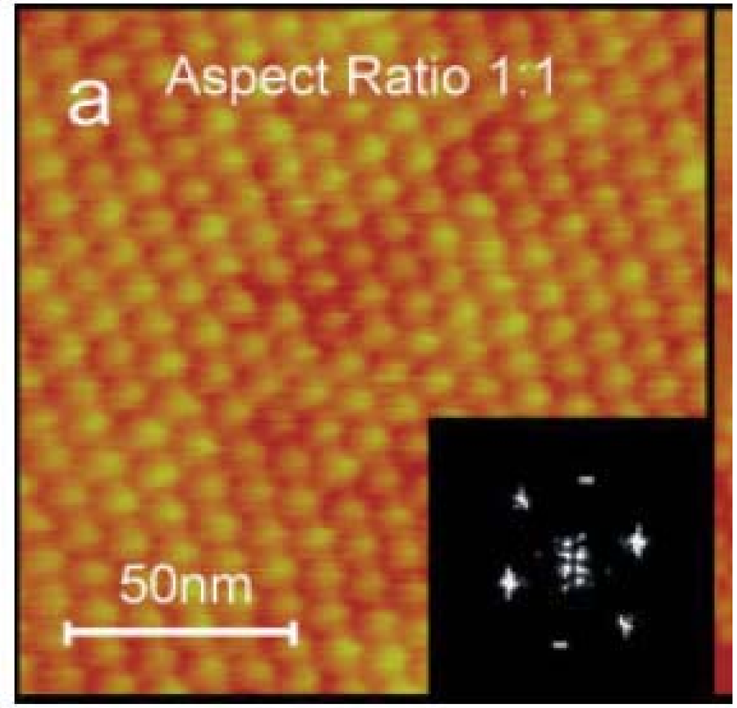
Cathode is typically a low work function material Al, Ca - injects electrons

Anode is typically a high work function material ITO - injects holes



Q-dot LEDs





Coe-Sullivan, et al. Advanced Functional Materials,
10.1002/adfm.200400468